

APPLICABLE STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-35°C TO +85°C (NOTES 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C (NOTE3)
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTES 2)	STORAGE HUMIDITY RANGE	40 % TO 70 % (NOTE3)
	VOLTAGE	150 V AC	CURRENT	1 A

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
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CONSTRUCTION

GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.		X	X

ELECTRIC CHARACTERISTICS

CONTACT RESISTANCE	100 mA (DC OR 1000 Hz)	30 mΩ MAX.		
CONTACT RESISTANCE MILLIVOLT LEVEL METHOD.	20 mV MAX, 1 mA (DC OR 1000 Hz).		X	-
INSULATION RESISTANCE	100 V DC.	500 MΩ MIN.	X	-
VOLTAGE PROOF	500 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	-

MECHANICAL CHARACTERISTICS

MECHANICAL OPERATION 	30 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	-

ENVIRONMENTAL CHARACTERISTICS

RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55→ 5 TO 35→ +85→ 5 TO 35 °C TIME 30→ 10 TO 15→ 30→ 10 TO 15 min. UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.		X	-
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING «REFLOW AREA» MAX 250°C 10 sec MAX 230°C MIN 60 sec MAX «PREHEATING AREA» 170°C TO 190°C 60 sec TO 120 sec PUT THROUGH IN REFLOW FURNACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350±5 °C, SOLDERING TIME : 5±1 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	-
SOLDERABILITY	SOLDERING TEMPERATURE : 230±5°C DURATION OF IMMERSION : SILDERING, FOR 3sec.	SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	X	-


REMARKS

NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT

NOTE2:NO CONDENSING

NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD.



AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION

COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
 1	DIS-H-008930	MI. SAKIMURA	TS. FUKUSHIMA	14. 07. 18

Unless otherwise specified, refer to IEC 60512.

APPROVED	KJ. KATAYOSE	05. 01. 05
CHECKED	TY. OMA	05. 01. 05
DESIGNED	TS. KUMAZAWA	05. 01. 05
DRAWN	TS. KUMAZAWA	05. 01. 05

Note QT:Qualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.	ELC4-160307-16
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	SPECIFICATION SHEET	PART NO.	DF14-*P-1. 25H (26)
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL538-  1/1